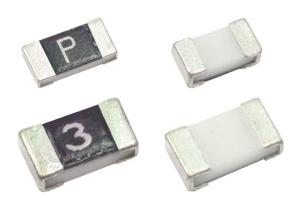




Fast Acting Thin Film Chip Fuses



FEATURES

- 3 sizes: 0402, 0603, and 1206
- Maximal protection as fuses are designed to open in t < 1 min at 200 % overload



- UL 248-14 compliant
- From 0.315 A to 7 A
- Low resistance
- Body temperature rising < 75 °C at 100 % rated current
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

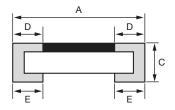
LINKS TO ADDITIONAL RESOURCES



S2F thin film chip fuses are designed to ensure circuit continuity with minimal resistance and reliable interruption under overload condition. Particularly adapted to be compatible with numerous applications in the sector of electronics. They comply with industrial and government standards, as well as Vishay quality and reliability requirements. For very fast acting see S3F datasheet.

TECHNICAL SPECIFICATIONS							
DESCRIPTION	S2F0402	S2F0603	S2F1206				
Imperial size	0402	0603	1206				
Rated current I _N range	0.315 A to 4.00 A	0.40 A to 5.00 A	0.50 A to 7.00 A				
Rated voltage $U_{\text{max.}}$ DC	32 V	32 V and 50 V	32 V and 63 V				
Cold resistance at $I \le 0.1 \times I_N$	12 m Ω to 690 m Ω	11 m Ω to 496 m Ω	7.5 m Ω to 517 m Ω				
Fusing time	Open within 1 min at 200 % rated power						
Body temperature rise	< 75 °C at 100 % rated current						
Operating temperature range	-25 °C to 125 °C with proper derating factor						
Approved UL 248-14 recognition file		E548286					

DIMENSIONS





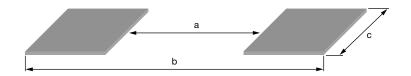
DIMENSIONS AND TOLERANCES in millimeters (inches)									
TYPE	A B C D E								
S2F0402	1.00 ± 0.10 (0.039 ± 0.004)	0.52 ± 0.05 (0.020 ± 0.002)	0.35 ± 0.05 (0.014 ± 0.002)	0.20 ± 0.10 (0.008 ± 0.004)	0.25 ± 0.10 (0.010 ± 0.004)				
S2F0603	1.60 ± 0.10 (0.063 ± 0.004)	0.80 ± 0.10 (0.031 ± 0.004)	0.45 ± 0.10 (0.018 ± 0.004)	0.30 ± 0.20 (0.012 ± 0.008)	0.35 ± 0.20 (0.014 ± 0.008)				
S2F1206	3.10 ± 0.10 (0.122 ± 0.004)	1.55 ± 0.10 (0.061 ± 0.004)	0.60 ± 0.10 (0.024 ± 0.004)	0.50 ± 0.30 (0.020 ± 0.012)	0.50 ± 0.20 (0.020 ± 0.008)				



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MECHANICAL SPECIFICATIONS				
Substrate	Ceramic			
Technology	Thin film			
Termination	Cu / Ni plating			

LAND PATTERN DIMENSIONS



SUGGESTED LAND PATTERN DIMENSIONS in millimeters (inches)								
TYPE	TYPE a b c							
S2F0402	0.55 to 065	1.40 to 1.60	0.74 to 0.94					
	(0.022 to 0.026)	(0.055 to 0.063)	(0.029 to 0.037)					
S2F0603	0.85 to 0.95	2.00 to 2.20	1.50 to 1.70					
	(0.033 to 0.037)	(0.079 to 0.087)	(0.059 to 0.067)					
S2F1206	0.95 to 1.05	4.40 to 5.00	2.30 to 2.50					
	(0.037 to 0.041)	(0.173 to 0.197)	(0.091 to 0.098)					

S2F0402 RATING							
PART DESIGNATION	MARKING	RATED CURRENT (A)	FUSING TIME	RESISTANCE (1) (m Ω), TOLERANCE: ± 25 %	RATED VOLTAGE (V _{DC})	BREAKING CAPACITY	
S2F040232VA315TT	D	0.315		690			
S2F040232VA500TT	F	0.500		340			
S2F040232VA750TT	V	0.750		140			
S2F040232VA800TT	K	0.800	0.800	100			
S2F040232V1A00TT	L	1.000		95			
S2F040232V1A25TT	<u>M</u>	1.250	Open within	57			
S2F040232V1A50TT	Р	1.500	1 min at 200 %	45	32	32 V _{DC} , 35 A	
S2F040232V1A60TT	N	1.600	rated current	44			
S2F040232V2A00TT	S	2.000		33			
S2F040232V2A50TT	Т	2.500		25			
S2F040232V3A00TT	3	3.000		19			
S2F040232V3A15TT	U	3.150		18			
S2F040232V4A00TT	W	4.000		12			

Note

⁽¹⁾ Resistance value was measured with less than 10 % of rated current





S2F0603 RATING							
PART DESIGNATION	MARKING	RATED CURRENT (A)	FUSING TIME	RESISTANCE ⁽¹⁾ (m Ω), TOLERANCE: \pm 25 %	RATED VOLTAGE (V _{DC})	BREAKING CAPACITY	
S2F060350VA400TT	E	0.40		496	50	50 V 50 A	
S2F060350VA500TT	F	0.50		290	30	50 V _{DC} , 50 A	
S2F060332VA630TT	I	0.63		205			
S2F060332VA800TT	K	0.80		132			
S2F060332V1A00TT	L	1.00		84			
S2F060332V1A25TT	<u>M</u>	1.25	25	63			
S2F060332V1A50TT	Р	1.50	Open within	50.5			
S2F060332V1A60TT	N	1.60	1 min at 200 % rated current	45	20	20.1/ 50.4	
S2F060332V2A00TT	S	2.00	rated current	34	32	32 V _{DC} , 50 A	
S2F060332V2A50TT	Т	2.50		24.5			
S2F060332V3A00TT	3	3.00		20			
S2F060332V3A15TT	U	3.15		19			
S2F060332V4A00TT	W	4.00		13			
S2F060332V5A00TT	Υ	5.00		11			

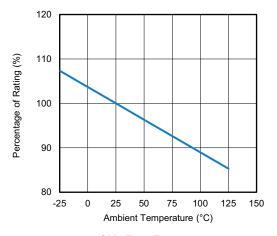
S2F1206 RATING							
PART DESIGNATION	MARKING	RATED CURRENT (A)	FUSING TIME	RESISTANCE (1) (m Ω), TOLERANCE: \pm 25 %	RATED VOLTAGE (V _{DC})	BREAKING CAPACITY	
S2F120663VA500TT	F	0.50		517			
S2F120663VA800TT	K	0.80		211			
S2F120663V1A00TT	L	1.00 1.25		132	63	60.1/ 50.4	
S2F120663V1A25TT	M			95	03	63 V _{DC} , 50 A	
S2F120663V1A50TT	Р	1.50	Open within	76			
S2F120663V2A00TT	S	2.00	1 min at 200 %	40.5			
S2F120632V2A50TT	Т	2.50	rated current	31.5			
S2F120632V3A00TT	3	3.00		23.25			
S2F120632V4A00TT	W	4.00		16	32	32 V _{DC} , 50 A	
S2F120632V5A00TT	Υ	5.00		12			
S2F120632V7A00TT	Z	7.00		7.5			

Note

TEMPERATURE DERATING

Normal ambient temperature: 25 °C

Operating temperature range: -25 °C to 125 °C, with proper derating factor as below:



Chip Fuse Temperature

⁽¹⁾ Resistance value was measured with less than 10 % of rated current



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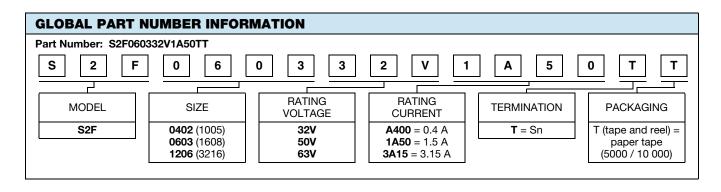
PERFORMANCES						
TESTS	CONDITIONS	REQUIREMENTS PERMISSIBLE CHANGES				
Carrying capacity	Rated current, 4 h	No fusing				
Fusing time	200 % of its rated current	Within 5 s				
Interrupting ability	After the fuse is interrupted, rated voltage applied for 30 s again	No mechanical damages				
Bending test	Distance between holding points: 90 mm Bending: 3 mm, 1 time, 30 s	No mechanical damages				
Resistance to solder heat	260 °C ± 5 °C, 10 s ± 1 s	± 20 %				
Solderability	235 °C ± 5 °C, 2 s ± 0.5 s 245 °C ± 5 °C, 2 s ± 0.5 s (lead (Pb)-free)	95 % coverage minimum				
Temperature rise	100 % of its rated current, measurement of surface temperature	< 75 °C				
Resistance to dry heat	105 °C ± 5 °C, 1000 h	± 20 %				
Resistance to solvent	23 °C ± 5 °C in isopropyl alcohol, 90 s	No evident damages on protective coating and marking				
Residual resistance	DC measurement after fusing	10 $k\Omega$ and more				
Thermal shock	-25 °C / 25 °C / 125 °C / 25 °C, 10 cycles	$\frac{\Delta R}{R}$ < 10 %				

PACKAGING				
SIZE	MOQ	TAPE WIDTH	TAPE PITCH	PACKAGING DIMENSIONS
0402	10 000		2 mm	Ø 180 mm / 7"
0603	5000	8 mm	4 mm	Ø 180 mm / 7"
1206	5000		4 mm	Ø 180 mm / 7"

Note

SOLDERING / MOUNTING PARAMETERS

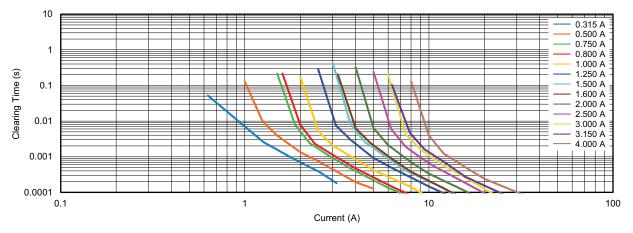
Please see the application note (<u>www.vishay.com/doc?52029</u>). The recommended reflow solder process parameters are displayed in pages 4 and 5.



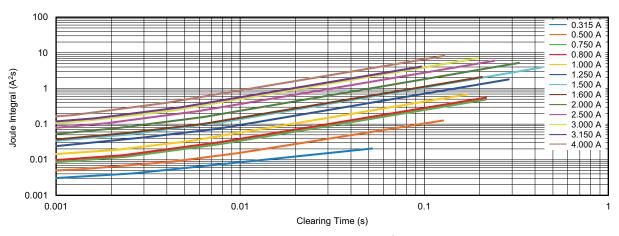
[•] Packaging is compliant to EIA-481 Rev. D (IEC 60286, part 3) standard



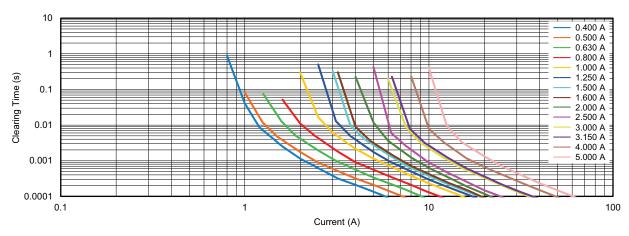
FUNCTIONAL PERFORMANCE



S2F04 (0402 Size) Chip Fuse I-t Curve

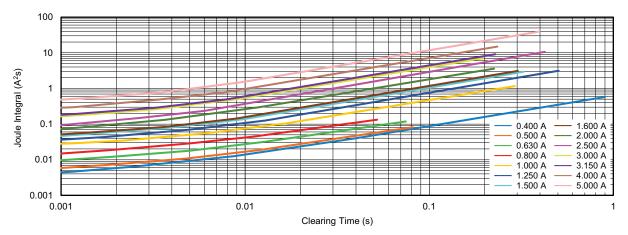


S2F04 (0402 Size) Chip Fuse t-I2t Curve

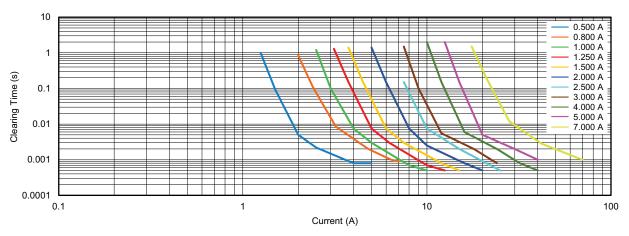


S2F06 (0603 Size) Chip Fuse I-t Curve

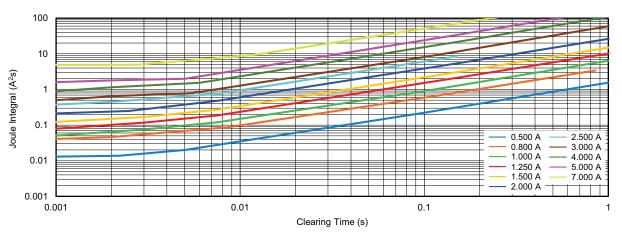




S2F06 (0603 Size) Chip Fuse t-I2t Curve



S2F12 (1206 Size) Chip Fuse I-t Curve



S2F12 (1206 Size) Chip Fuse t-I2t Curve

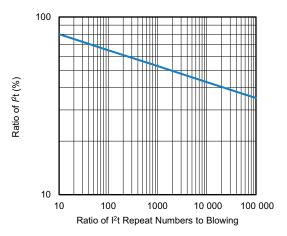




Typical Joule integral values $(\int_{t=0}^{t} i^2 . dt)$, measured at 10 times rated current, are displayed in the following table:

S2F FUSE /2t (A2s)							
PART NUMBER	TYPICAL I ² t (A ² s)	PART NUMBER	TYPICAL I ² t (A ² s)	PART NUMBER	TYPICAL /2t (A2s)		
S2F040232VA315TT	0.00203	S2F060350VA400TT	0.004	S2F120663VA500TT	0.011		
S2F040232VA500TT	0.00317	S2F060350VA500TT	0.005	S2F120663VA800TT	0.031		
S2F040232VA750TT	0.00402	S2F060332VA630TT	0.007	S2F120663V1A00TT	0.034		
S2F040232VA800TT	0.00532	S2F060332VA800TT	0.014	S2F120663V1A25TT	0.062		
S2F040232V1A00TT	0.00724	S2F060332V1A00TT	0.016	S2F120663V1A50TT	0.144		
S2F040232V1A25TT	0.01344	S2F060332V1A25TT	0.027	S2F120663V2A00TT	0.181		
S2F040232V1A50TT	0.01356	S2F060332V1A50TT	0.037	S2F120632V2A50TT	0.351		
S2F040232V1A60TT	0.01672	S2F060332V1A60TT	0.041	S2F120632V3A00TT	0.501		
S2F040232V2A00TT	0.01983	S2F060332V2A00TT	0.044	S2F120632V4A00TT	0.954		
S2F040232V2A50TT	0.03763	S2F060332V2A50TT	0.055	S2F120632V5A00TT	0.966		
S2F040232V3A00TT	0.05427	S2F060332V3A00TT	0.082	S2F120632V7A00TT	3.250		
S2F040232V3A15TT	0.06304	S2F060332V3A15TT	0.089				
S2F040232V4A00TT	0.08960	S2F060332V4A00TT	0.239				
		S2F060332V5A00TT	0.433				

Furthermore, for repeated numbers of inrush current, another specific derating must be applied:



Chip Fuse Clearing by Repeated Rush Current



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